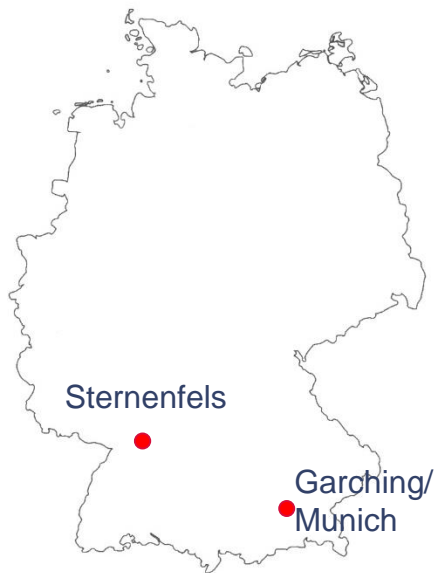


SUSS MICROTEC INVESTOR PRESENTATION

January 2018

- + International high tech equipment provider for the semiconductor industry
- + All major chip manufacturers are clients of ours
- + Global customer base with focus on Asia/Pacific
- + Production at two major sites in Germany and the USA



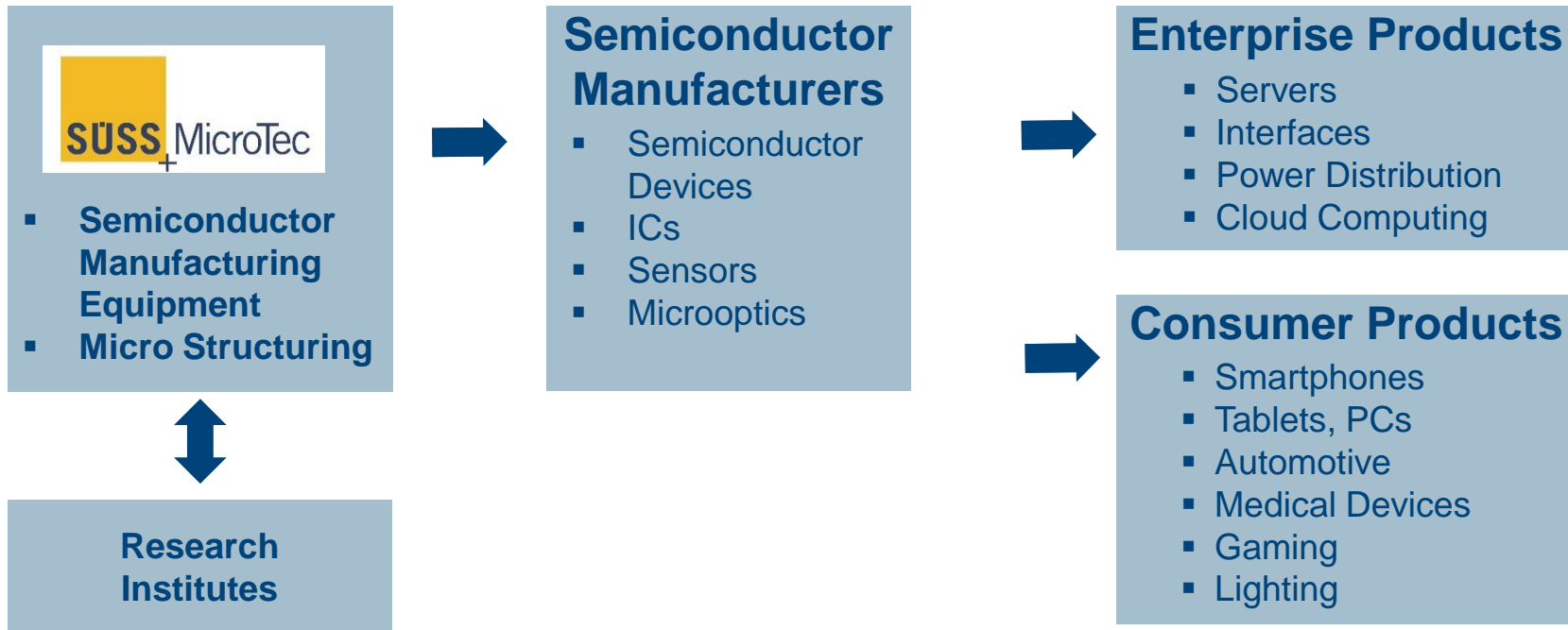
Germany



USA



Mask Cleaning Equipment: MaskTrack PRO



+ SUSS MicroTec:

- Key player in leading edge semiconductor manufacturing equipment
- Developer of highly innovative process solutions

+ Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec's equipment

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 33.7 € million
Sales 25.4 € million
Employees 102

EMEA

Order Entry 38.1 € million
Sales 43.1 € million
Employees 469

ASIA

Order Entry 89.3 € million
Sales 109.0 € million
Employees 140



*Figures refer to the fiscal year 2016

WE SUPPORT TECHNOLOGICAL CHANGE

Telecommunications



- Communication
- Mobility
- Networks

Data Processing



- Data processing
- Mobility
- Digitization
- Smart factory

Automotive



- Safety
- Comfort
- Energy efficiency
- Autonomous driving



since 1980s
(radiotelephones)



Since 1990s
(cellphones)



Today
(smartphones)

- + In the 1990s cellphones used to be large and heavy – today they are small and handy
- + Shift from pure telephone functionality to minicomputer with many functions
- + Video conferences, camera, navigation, internet access, electronic payment and many more
- + Sensors for gravity, acceleration, rotation, pressure
- + Countless APPs for many different applications
- + Modern packaging technologies -> number of electronic components rises constantly
- + **55% of all German citizens own a smartphone, only 8% don't have a cellphone** (Source: Bitkom)



1970/80s
(personal computer)



Since 2010
(tablets)



Future
(unlimited networking)

- + **Computers are getting smaller, more powerful and mobile -> laptop -> tablet**
- + **Computing power of a modern tablet >> mainframe of the moon mission Apollo 11 (1969)**
- + **Almost unlimited mobility, communication and networking**
- + **Thanks to progress in broadband networks: data volume rises continuously**
- + **Nowadays items start to communicate with one other: “internet of things”**
- + **Industry gets digitized, meaning that large amounts of data can be used for process optimization -> smart factory**



1980s
(first airbags)

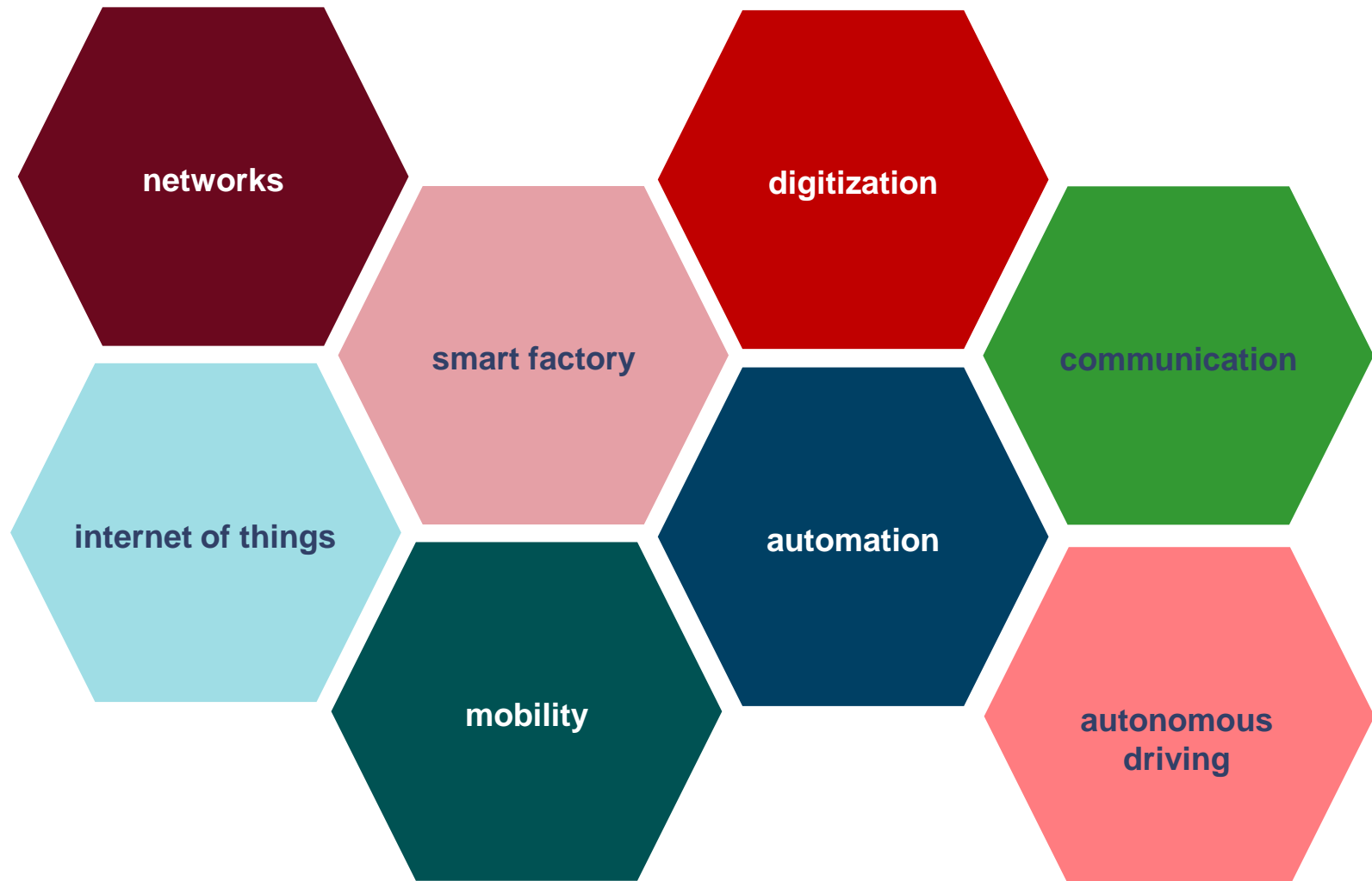


1989
(navigation)



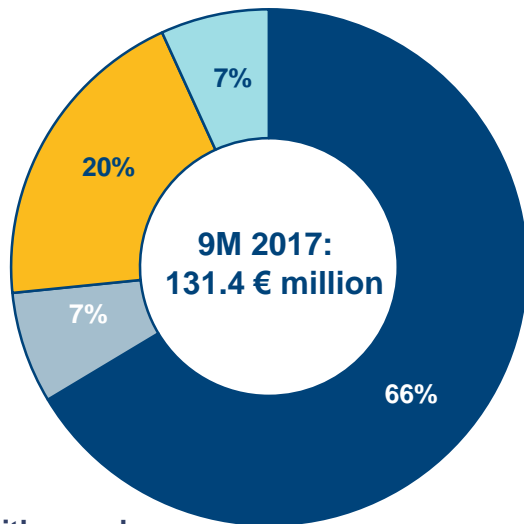
Future
(autonomous driving)

- + **Sensors are the senses of a computer: connection to the outside world happens via sensors**
- + **Example Car:**
 - **Sensor controlled electronics in cars improve comfort and safety**
 - **Engine control for reduced fuel consumption and lower emissions are not possible without sensors**
 - **In the future: autonomous driving for more flexibility, energy efficiency and safety**
- + **Applications for sensors are in the computer and automotive industry, medical applications, security systems, internet of things and smart factory**
- + **Number of MEMS sensors has been rising rapidly for years now**



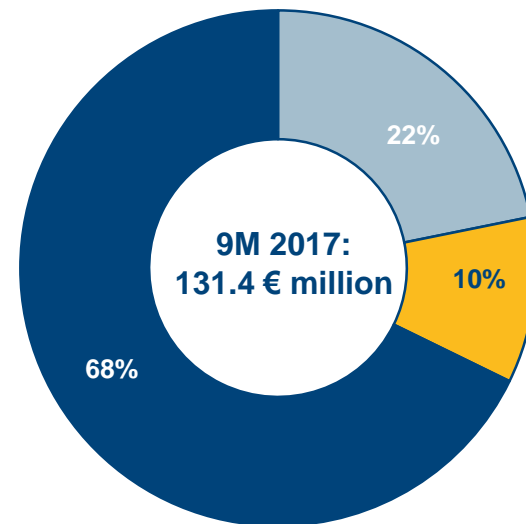
ORDER ENTRY BY SEGMENT AND REGION IN 9M 2017

Segments



- Lithography
- Fotomask Equipment
- Bonder
- Others

Regions



- Europe
- North America
- Asia/Pacific

Divisions

Photomask Equipment

Photomask Cleaning
Equipment

9M
2017

Order Entry: 9.2 € million
Sales: 16.7 € million
EBIT: 5.1 € million

Lithography

Laser
Processing
Equipment

Exposure
Systems

Coaters and
Developers

Order Entry: 87.2 € million
Sales: 74.8 € million
EBIT: 1.7 € million

Bonder

Wafer Bonding
Equipment

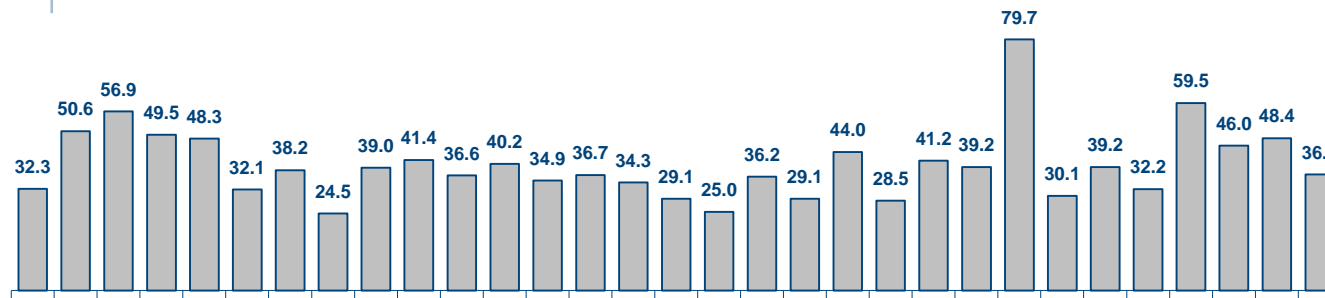
Order Entry: 26.0 € million
Sales: 12.9 € million
EBIT: 1.8 € million

SUSS MicroTec Group* 9M 2017

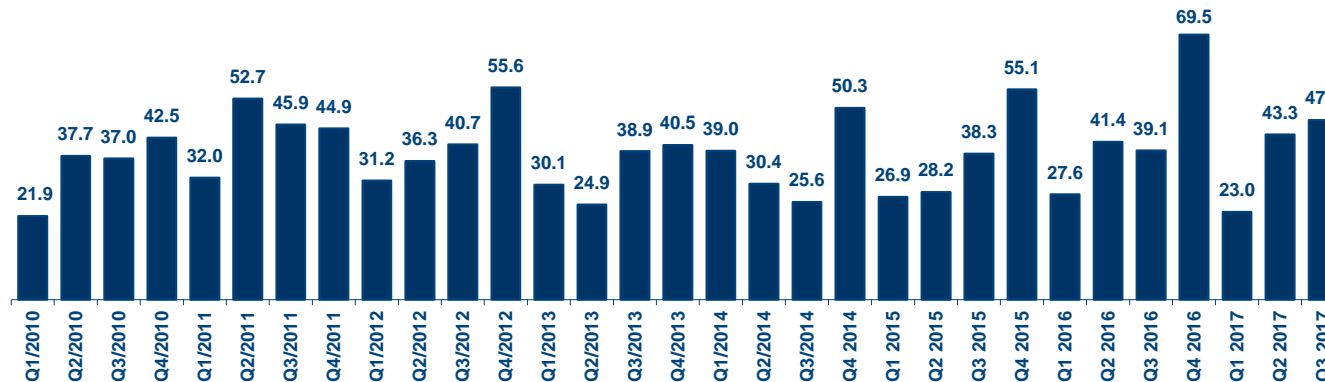
Order Entry: 131.4 € million
Sales: 113.4 € million
EBIT: 8.6 € million
EBIT margin: 7.6%

* Including Others

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



Order Entry
in € million

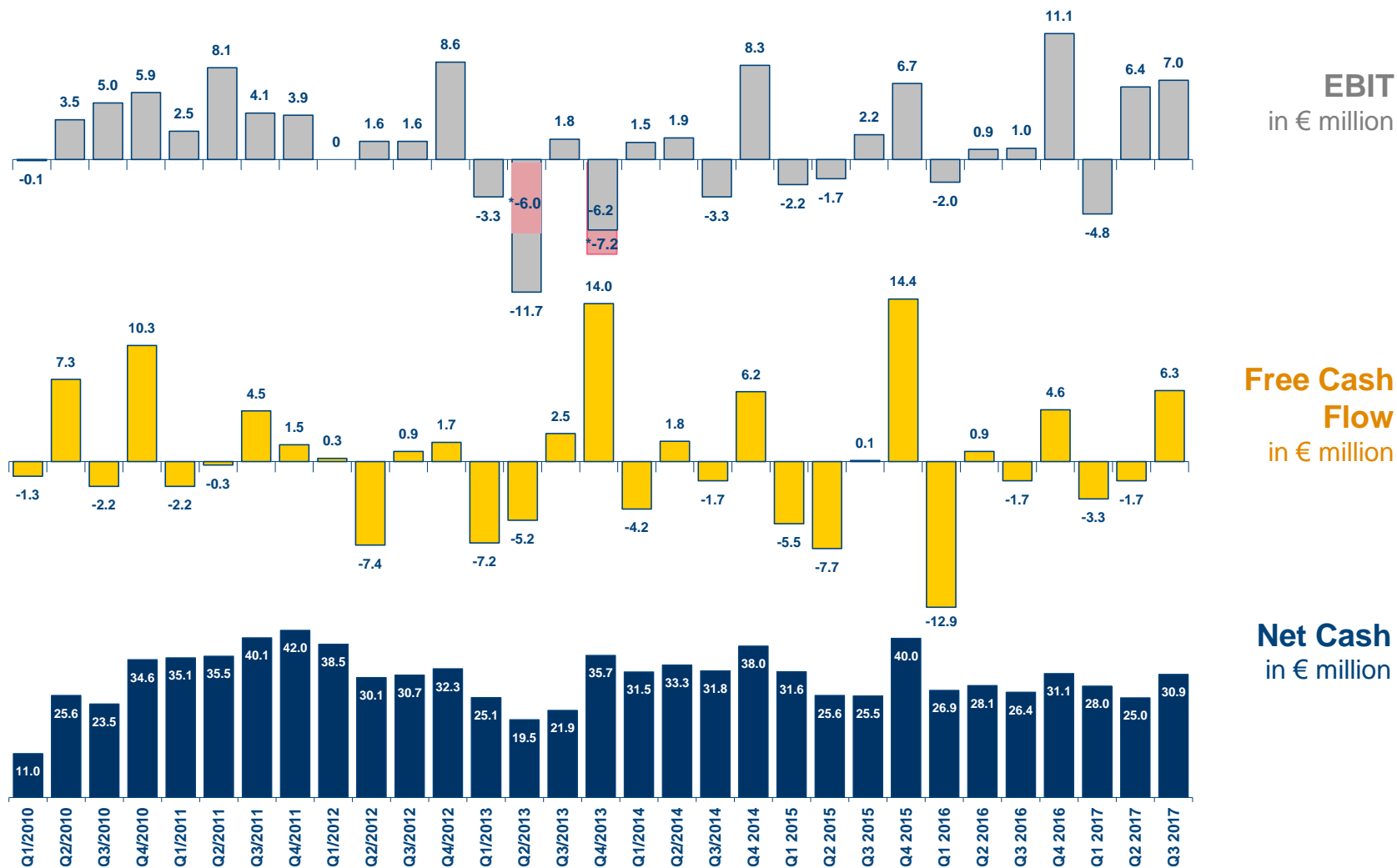


Sales
in € million



EBIT
in € million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding

Portable electronic products are driving component packaging towards new packaging technologies for integrating multiple functions (e.g. memory, analog and passive components: SiP)

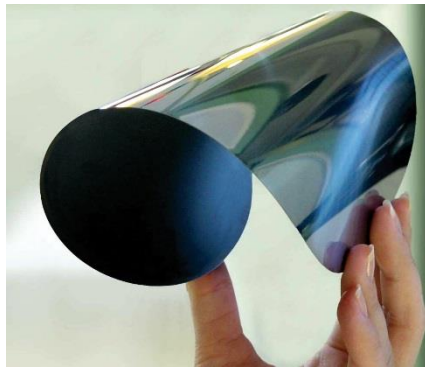
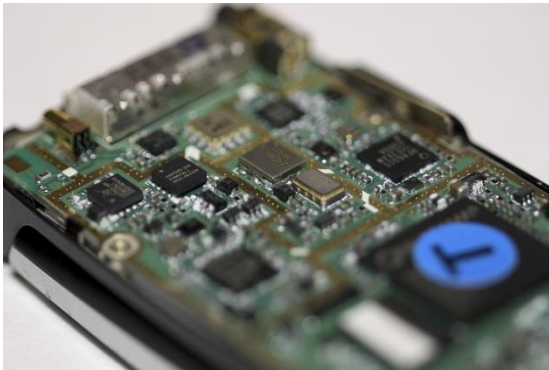
Fan Out Wafer Level Packaging (FOWLP)
Three Dimensional Thru Silicon Via (3D TSV)

Allows for:

- + Smaller form factors**
- + Multi-die package / SiP**
- + Increased I/O density (Fine line and space (L/S))**
- + Providing high capacity and high bandwidth packages**

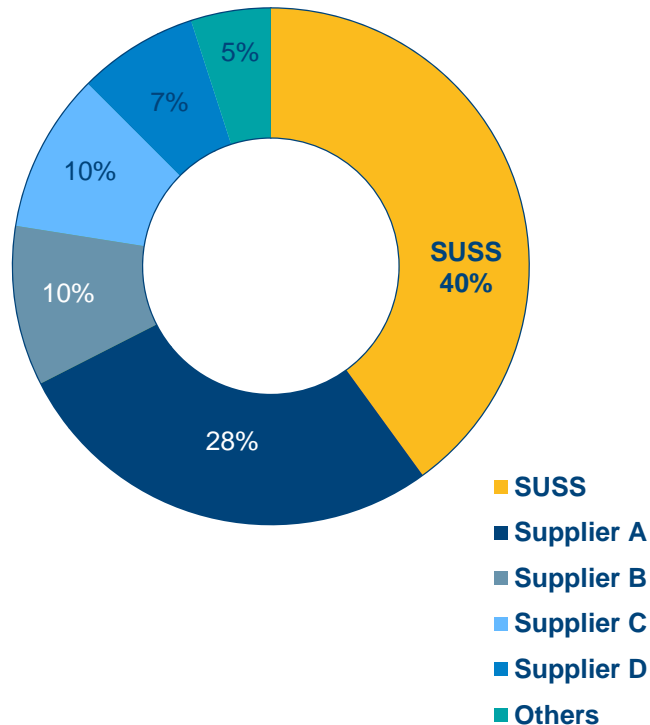
 **Trend will continue**

- + Since the early 1990s, advanced packaging methods have enabled smaller chip packages
 - SUSS was one of the drivers in the introduction of advanced packaging in the 1990s
 - SUSS was a founding member of SECAP (Semiconductor Equipment Consortium for Advanced Packaging)
 - SECAP supported the transition from "wire bonding" to "flip chip bonding"
- + Today, SUSS supports the transition from 2D to 2.5D and finally to 3D TSV (Thru Silicon Via)
 - SUSS works with the leading users of the 3D TSV technology
 - The first pilot lines are already installed and will be further optimized
 - SUSS is one of the leading equipment suppliers for this growth area
- + „Thin wafer handling “ and „temporary bonding“ are major elements of 3D stacking

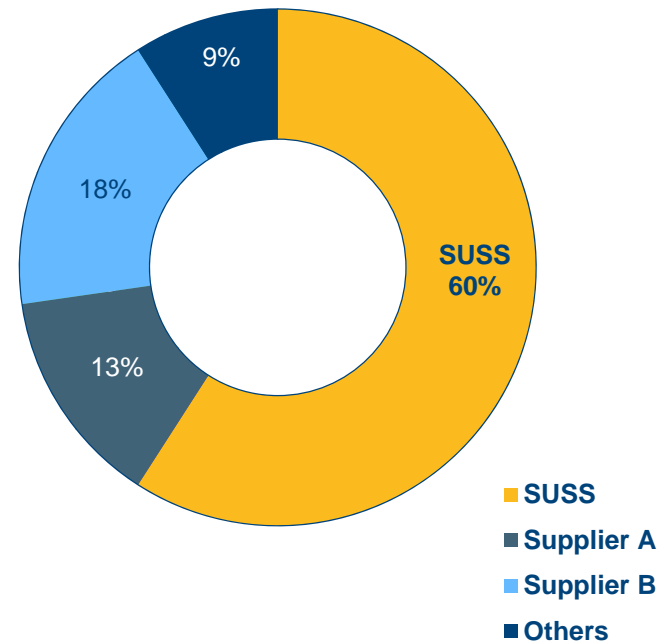


WORLD-WIDE MARKET SHARE TEMPORARY BONDING/ DEBONDING (TBDB) AUTO EQUIPMENT

TBDB Auto Tool Market Share 2017
for 2.5D and 3D TSV

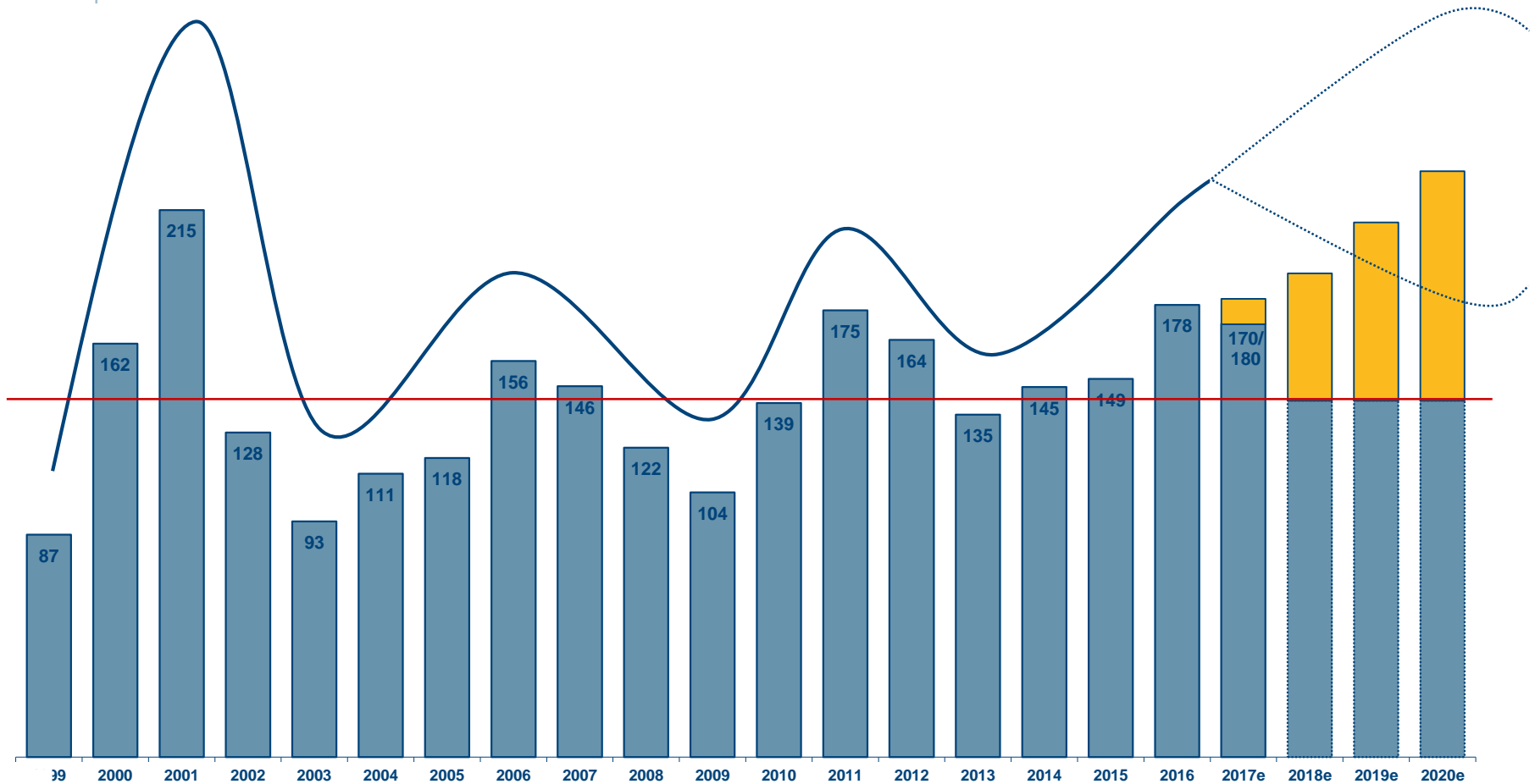


TBDB Auto Tool Market Share 2017
Top 3 IDMs – 3D TSV based memory



→ SUSS is the #1 equipment supplier for TBDB auto equipment for 2.5D, 3D and WLP applications

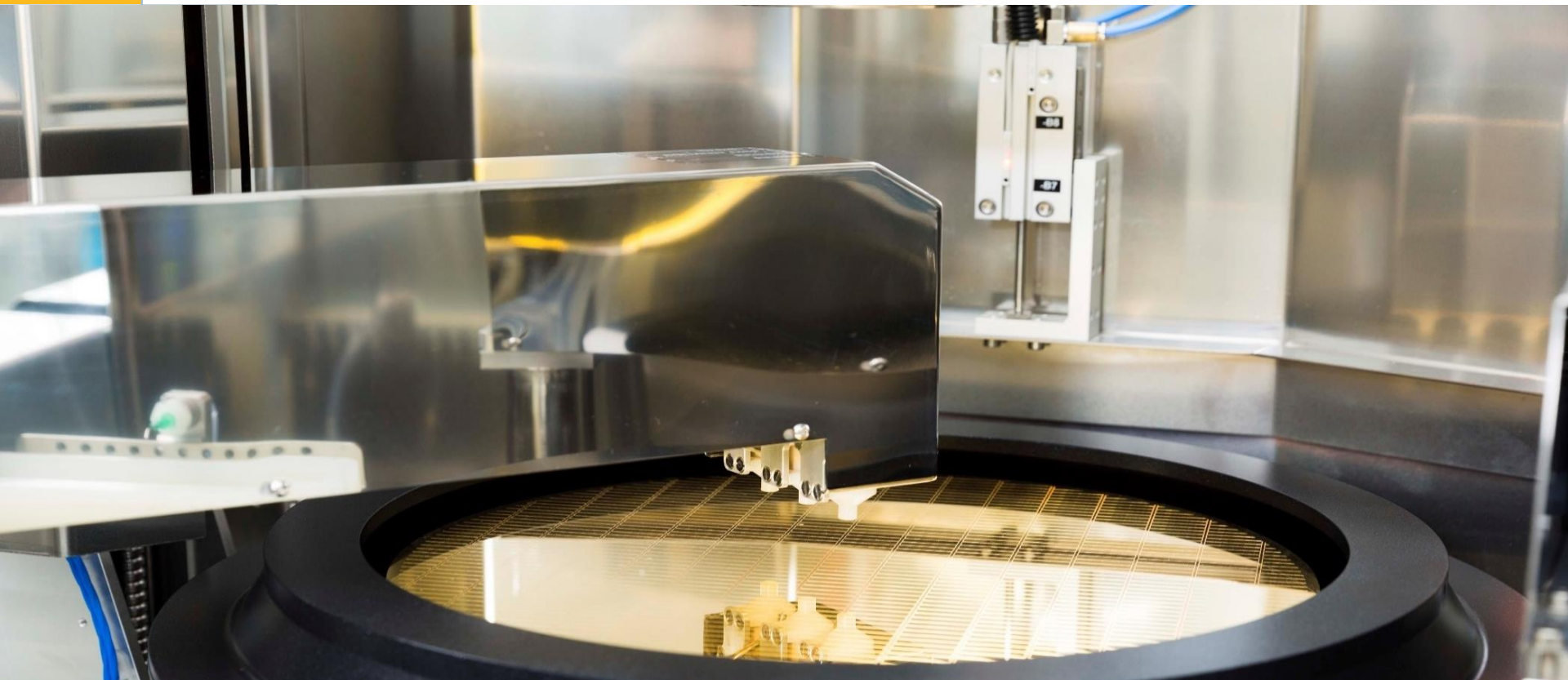
LONG TERM SALES DEVELOPMENT IN MIO. €



Average sales level 1999 – 2016: appr. € 140 million



- + Gartner again increased its expectations for growth in the semiconductor segment to 19.7% in 2017
- + This would mark a new record sales level of USD 411 billion for the semiconductor industry
- + Market growth is driven by automotive and industrial applications as well as memory chips and the internet of things
- + Semi expects a market growth of the semiconductor-equipment industry in 2017 of +19,8%
- + Wafer-level packaging and assembly will grow by +12,8% in 2017 after +3.9% in 2016 (according to Semi)
- + Yole expects the MEMS-market to grow by +12% (CAGR) from 2016 to 2021(unit growth)



- + Fiscal year 2017:** **Sales € ~ 16 million**
 EBIT ~ € 14 million
- + 4th quarter 2017:** **Order entry € > 69 million**



WE ARE SÜSS MICROTec

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Financial Calendar 2018

Quarterly Report 2018	3 May
Annual General Meeting 2018, Munich	6 Jun
Interim Report 2018	3 Aug
Nine-month Report 2018	7 Nov

KEY GROUP FIGURES AT A GLANCE

in € million	Q3 2017	Q3 2016	Delta
Order Intake	36.9	32.2	+14.6%
Order Backlog 9/30	--	--	--
Revenue	47.1	39.1	+20.5%
EBIT	7.0	1.0	>100%
<i>EBIT in % of Sales</i>	<i>14.9%</i>	<i>2.6%</i>	12.3%pts
Earnings after tax	4.5	-0.2	--
EPS in €	0.24	-0.01	--
Free Cash Flow*	6.3	-1.7	--
Net Cash	--	--	--
Employees 9/30	--	--	--

9M 2017	9M 2016
131.4	101.5
117.7	110.9
113.4	108.1
8.6	0.0
7.6%	0.0%
3.8	-3.3
0.20	-0.17
0.7	-13.7
30.9	26.4
762	720

*before consideration of transactions with interest-bearing securities

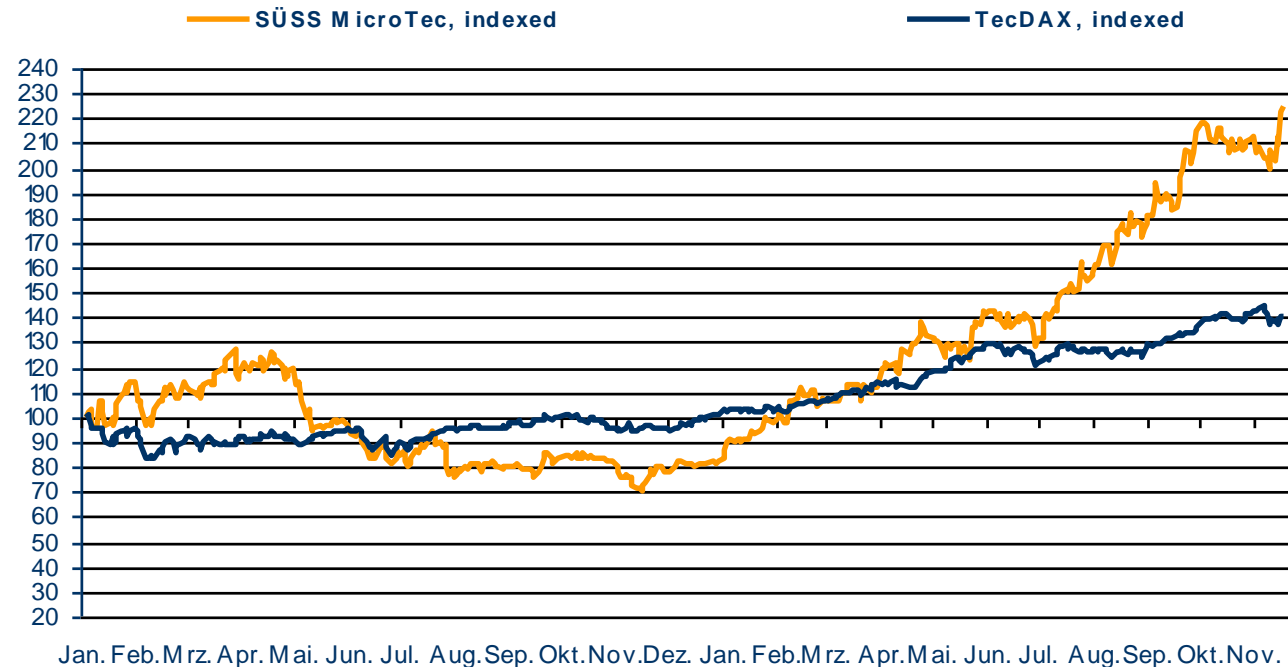
KEY GROUP FIGURES AT A GLANCE FY 2016

in € million	2016	2015	in %
Order Intake	161.1	188.6	-14.6%
Order Backlog 12/31	101.5	117.6	-13.7%
Revenue	177.6	148.5	19.6%
EBIT	11.1	5.0	>100%
<i>EBIT in % of Sales</i>	<i>6.3%</i>	<i>3.4%</i>	<i>2.9%pt</i>
Earnings after tax	5.0	0.2	>100%
EPS in €	0.26	0.01	>100%
Free Cash Flow*	-9.1	1.3	--
Net Cash	31.1	40.0	-22.3%

*before consideration of transactions with interest-bearing securities

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2016: 4.88 €)



Major Shareholders:

Universal	5.0%
Henderson	4.8%
Sycomore	4.7%
Lupus Alpha	3.2%
Luxempart	3.1%
Hansainvest	3.1%
Dimensional	3.0%

Average daily trading volume January 2016 – November 2017: ~ 146.000

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.